## Silicon Switching Diode 1N4150 DO-35 Glass Package <br> Applications <br> 1N4150-1

Used in general purpose applications,where a controlled forward characteristic and fast switching speed are important.

## Features

- Sixsigmaquality
- Metallurgically bonded
- BKC's Sigma Bond ${ }^{\text {TM }}$ plating for problem free solderability
- LL-34/35 MELF SMD available
- Full approval to Mil-S-19500/231
- Available up to JANTXV-1 levels
- "S" level screening available to Source Control Drawings

| Maximum Ratings |  | Symbol | 1 Value | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Peak Inverse Voltage |  | PIV | 75 (Min.) | Volts |
| Average Rectified Current |  | $\mathrm{I}_{\text {Ava }}$ | 200 | mAmps |
| Continuous Forward Current |  | $\mathrm{I}_{\text {Fdc }}$ | 400 | mAmps |
| Peak Surge Current ( $\mathrm{t}_{\text {neak }}=1 \mathrm{sec}$.) |  | $\mathrm{I}_{\text {peak }}$ | 0.5 | Amp |
| BKC Power Dissipation $\mathrm{T}_{L}=50^{\circ} \mathrm{C}, \mathrm{L}=3 / 8^{\prime \prime}$ from body |  | $\mathrm{P}_{\text {tot }}$ | 500 | mWatts |
| Operating Temperature Range |  | $\mathrm{T}_{0}$ | -65 to +200 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range |  | $\mathrm{T}_{\text {st }}$ | -65 to +200 | ${ }^{\circ} \mathrm{C}$ |
| Electrical Characteristics @ $25^{\circ} \mathrm{C}$ | Symbo | Minimum | Maximum | Unit |
| Forward Voltage Drop @ $I_{F}=1.0 \mathrm{~mA}$ <br> Forward Voltage Drop @ $I_{F}=10 \mathrm{~mA}$ <br> Forward Voltage Drop @ $I_{F}=50 \mathrm{~mA}$ <br> Forward Voltage Drop @ $I_{F}=100 \mathrm{~m}$ <br> Forward Voltage Drop @ $I_{r}=200 \mathrm{~mA}$ | $V_{F}$ | 0.54 | 0.62 | Volts |
|  | $V_{F}$ | 0.66 | 0.74 | Volts |
|  | $V_{F}$ | 0.76 | 0.86 | Volts |
|  | $V_{\text {F }}$ | 0.80 | 0.92 | Volts |
|  | V | 0.87 | 1.0 | Volts |
| Reverse Leakage Current @ $\mathrm{V}_{\mathrm{R}}=50 \mathrm{~V}$ | $I_{\text {r }}$ |  | 0.1 (100@ $150{ }^{\circ} \mathrm{C}$ ) | $\mu \mathrm{A}$ |
| Breakdown Voltage @ Ir $=0.1 \mathrm{~mA}$ | PIV | 75 |  | Volts |
| Capacitance @ $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{mHz}$ | $\mathrm{C}_{\text {T }}$ |  | 2.5 | pF |
| Reverse Recovery time (note 1)Reverse Recovery time (note 2,3)Forward Recovery time (note 4) | ${ }_{\text {tr }}$ |  | 4.0 | nSecs |
|  | $t_{\text {r }}$ |  | 6.0 | nSecs |
|  | $\mathrm{V}_{\mathrm{fr}}$ |  | 10 | nSecs |

Note 1: Per Method 4031-A with $I_{F}=I_{R}=10$ to $200 \mathrm{~mA}, R_{L}=100$ Ohms,recover to 0.1 If.
Note 2: Per Method 4031-A with $I_{F}=I_{R}=200$ to $400 \mathrm{~mA}, R_{L}=100$ Ohms, recover to 0.1 If.
Note 3: Per Method 4031-A with $\mathrm{I}_{\mathrm{F}}=10 \mathrm{microA}, \operatorname{lr}=1.0 \mathrm{~mA}$, recover to 0.1 mA .
Note 4: Per Method 4026 with $I_{F}=200 \mathrm{~mA}, \mathrm{Ir}=1.0 \mathrm{~mA}$, recover to 0.1 mA .
Microsemi

